



Features::

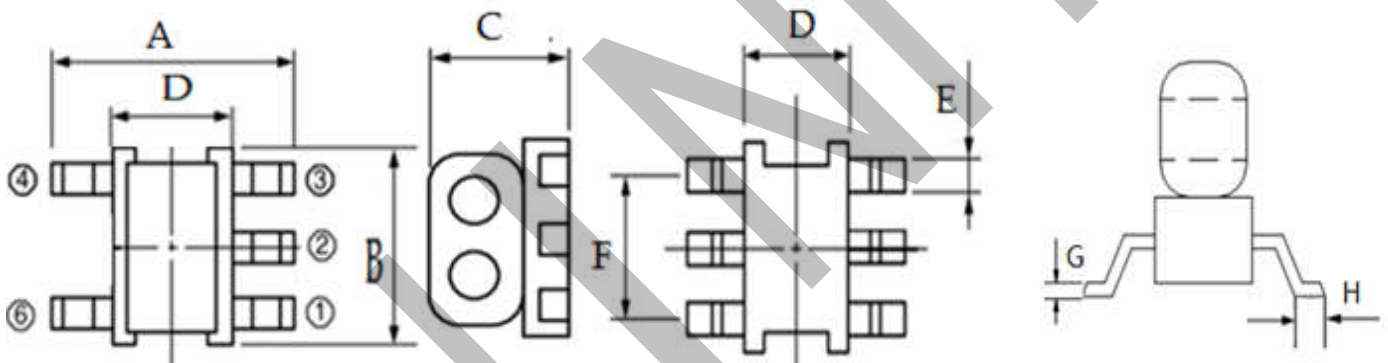
- ◆ 1: 1 Impedance
- ◆ 75Ω Characteristic Impedance
- ◆ Frequency: 50 to 1250 MHz
- ◆ RF power: 0.25W
- ◆ DC current: 30mA
- ◆ Insertion loss: 1.3dB Max; Input Return loss: 11.0dB Min
- ◆ Operating temperature range: -40°C to +85°C
- ◆ Storage temperature range: -55°C to +100°C



Applications:

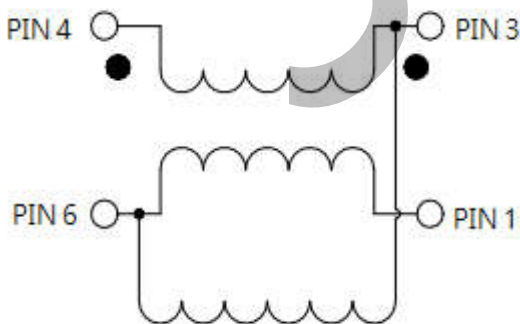
- ◆ For broadband and wireless communications
- ◆ For VHF/UHF receivers/transmitters and push-pull amplifiers

Dimension Diagram (Unit:mm) :

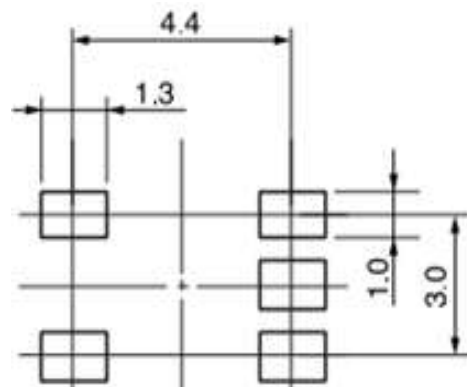


A=5.30±0.20 B=4.30±0.20 C=3.50±0.20 D=2.80±0.20 E=0.55±0.05 F=3.00±0.05 G=0.25±0.05 H=0.60±0.05

Electrical structure:



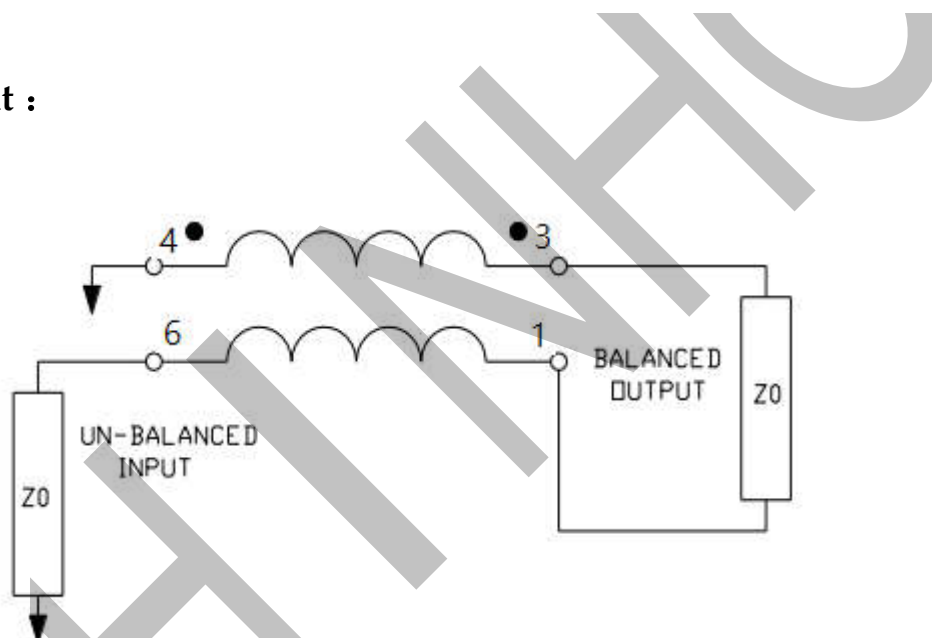
Recommended layout:



Pin configuration

Pin no.	Function
1	Secondary dot (Output 1)
2	Not connected
3	Secondary (Output 2)
4	Primary (Ground)
6	Primary dot (Input)

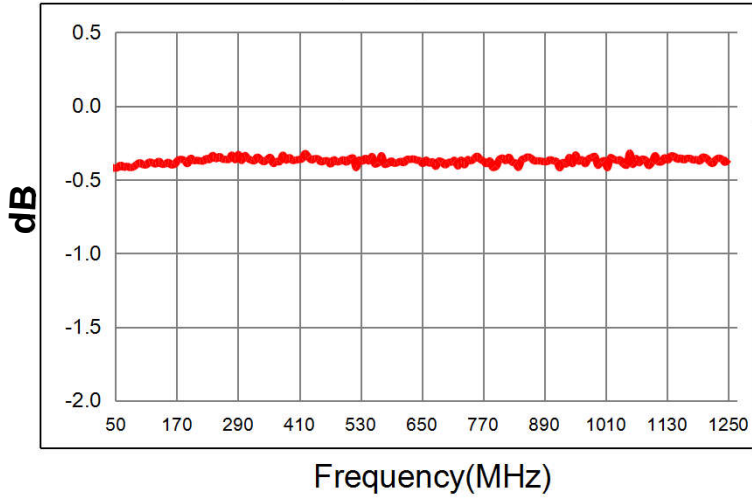
Application circuit :



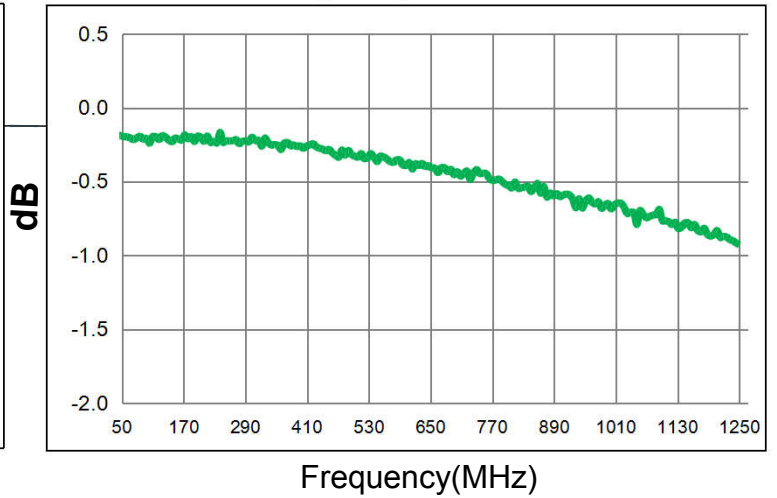
Electrical Specifications: $T_A = 25^\circ\text{C}$ $Z_0 = 75\Omega$

Parameter	Test Conditions	Units	Min	Typ	Max
Main line Loss(out1)	50-1250MHz	dB	—	0.4	1.0
Main line Loss(out2)	50-1250MHz	dB	—	0.7	1.5
Amplitude Balance	50-1250MHz	dB	—	± 0.5	± 0.5
Phase Balance	50-1250MHz	Degrees	—	± 2.5	± 6.0
Input Return Loss	50-1250MHz	dB	16.0	25.0	—

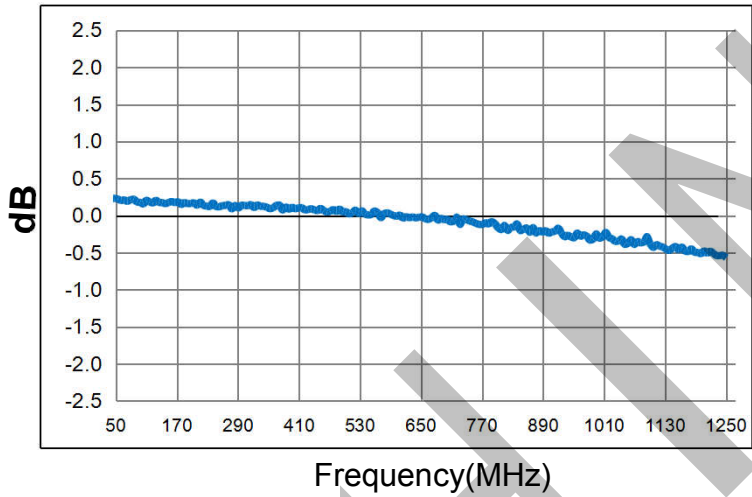
Main line Loss(out1)



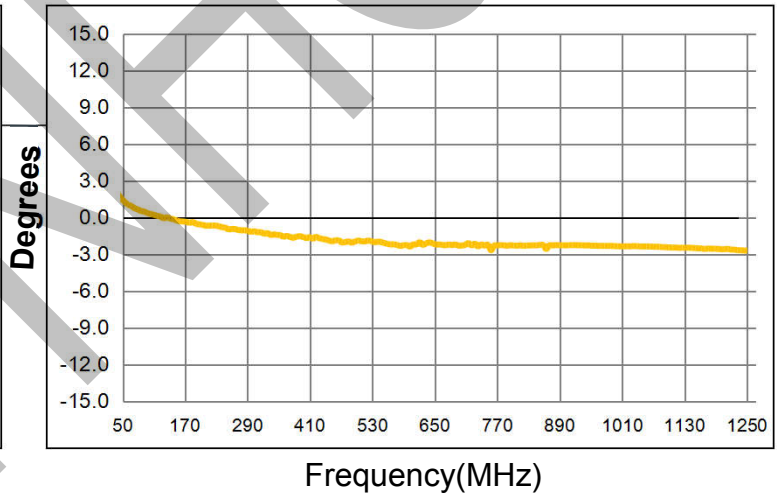
Main line Loss(out2)



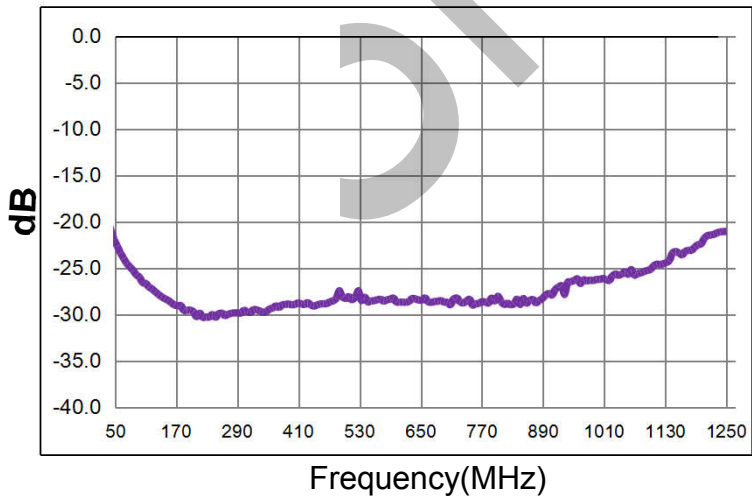
Amplitude Balance



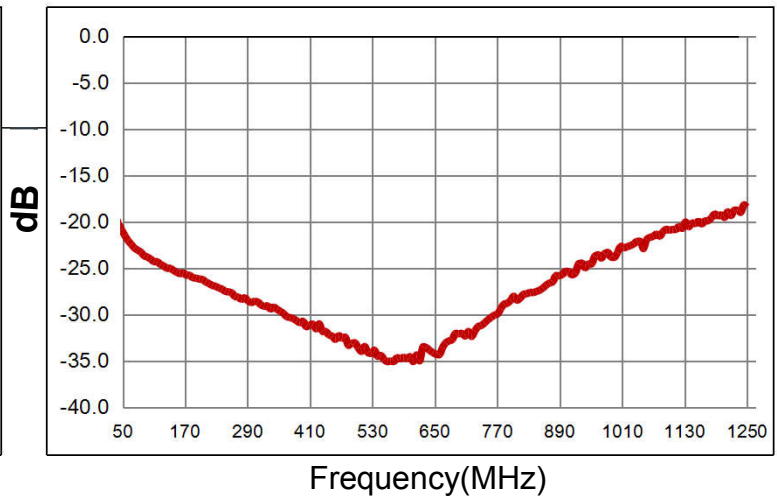
Phase Balance



Input Return Loss



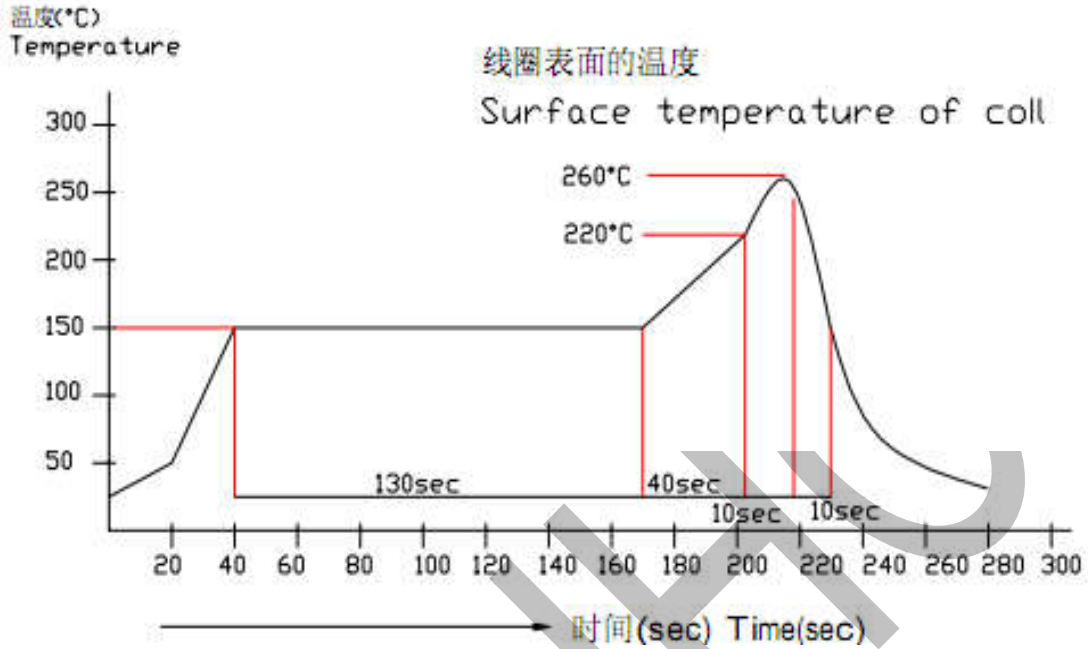
Sdd22



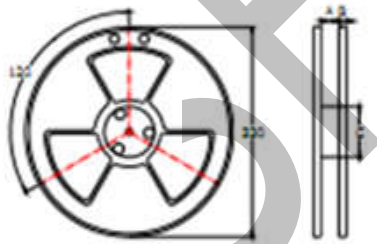
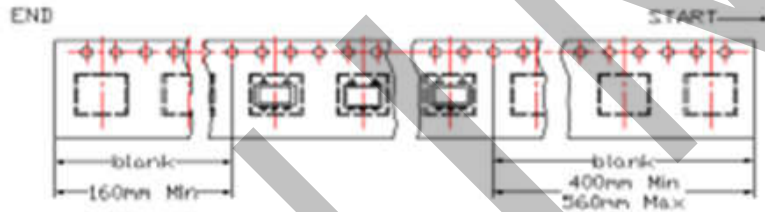
Recommended Soldering Temperature Graph:

建议迴焊条件

The condltion of reflow
(Recommendation)



Packging Dimension For Caeer Tape(UNIT:mm):



SPEC	8	12	16	24	32	44	56	72
DIM A±0.1	8.5	12.5	16.5	24.5	32.5	44.5	56.5	72.5
DIM B±0.1	2.3	2.3	2.3	2.3	2.3	2.3	2.3	2.3
DIM C±0.1	100	100	100	100	100	100	100	100

QUANTITY
2000PCS/Reel

15 reel/Big carton/60000pcs